

SURFBOARDS®

THE BREADBOARDING MEDIUM FOR SURFACE MOUNT™



33000 SERIES APPLICATION SPECIFIC ADAPTERS

IDS33110
REV A-10-2011

MODEL **33110**

10 LEAD .4 mm PITCH
4 SIDED DEVICES

ACCEPTS

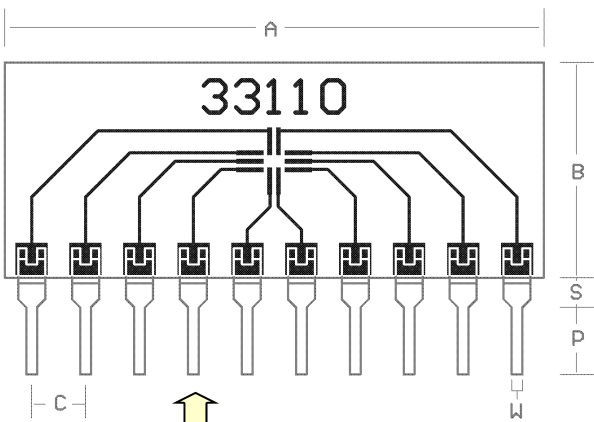
- ANALOG **LFCSP_UQ 1.3x1.6MM (CP-10-10)**
- FAIRCHILD **10LD UMLP, QUAD 1.4x1.8MM**
- ON SEMI **UQFN10 1.4x1.8,0.4P**
WQFN10 1.4x1.8,0.4P
- TEXAS INST. **RSW (PUQFN-N10)**

PARTIAL LISTING

ALWAYS CONSULT DEVICE DATA SHEET TO INSURE PROPER FIT

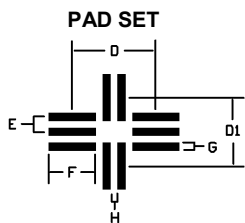
Feature Pins on .1 in. Centers designed for use with Solderless breadboards, Conventional Breadboards, and Sockets with standard .1 in. centers.

Use For Prototyping, Device Test or Evaluation and SMD to Through Hole Conversion.



SINGLE-IN-LINE (SIP) PINS
ON .100 in. CENTERS

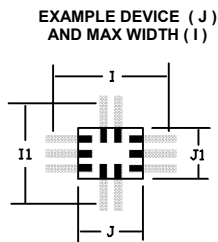
DRAWINGS
NOT TO
SCALE



MOUNTING PADS ARE OVERSIZED IN LENGTH TO ACCEPT A WIDER RANGE OF DEVICE WIDTHS AND TOLERANCES AND TO PERMIT HAND SOLDERING.
[SEE WEBSITE FOR SOLDERING SUGGESTIONS](#)

BOARD SPECIFICATIONS

BOARD MATERIAL: .8mm, +/- .13mm .031in +/- .005 in. Thick G-10 FR-4 Glass Epoxy or equivalent.
CIRCUITS: 1 oz. Copper with RoHS compliant Lead Free solder coating. Patten Position on board +/- .5mm .020in.



RoHS
Compliant
EC 2002/95

FIG.	MM	IN.	NOTE:
A	25.4	1.0	BOARD WIDTH +/- .5mm .020in.
B	10.16	.400	BOARD HEIGHT +/- .5mm .020in.
C	2.54	.100	SIP PIN SPACE +/- .20mm .008in.
D	2.3	.090	PAD CENTERLINE
D1	1.88	.074	PAD CENTERLINE OTHER AXIS
E	.4	.016	DEVICE LEAD PITCH
F	1.3	.051	PAD LENGTH
G	.225	.009	PAD WIDTH
H	.175	.007	GAP
I	3.15	.124	MAX LEAD WIDTH
I1	2.75	.108	MAX LEAD WIDTH OTHER AXIS
J	1.8	.070	TYPICAL LEAD WIDTH
J1	1.4	.055	TYPICAL LEAD WIDTH OTHER AXIS
P	3.3	.130	LENGTH FROM SHOULDER +/- .5mm .020in.
S	1.57	.062	PIN SHOULDER HEGHT
W	.5	.020	PIN WIDTH

TOLERANCES: If not noted are +/- 20%. Nominal values are given. Controlling unit is Millimeters. Values rounded to nearest decimal. Slight Variations due to manufacturing process can occur.

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